

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
GUANGWEI XU	05/24/2018
ZHIHENG HAN	05/24/2018
WEI WANG	05/24/2018
CONGYAN LU	05/24/2018
LINGFEI WANG	05/24/2018
LING LI	05/24/2018
MING LIU	05/24/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES
<b>Street Address:</b>	NO. 3 BEITUCHENG WEST ROAD, CHAOYANG DISTRICT
<b>City:</b>	BEIJING
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	100029
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16065582
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	6124553800
<b>Email:</b>	ykase@hsmi.com
<b>Correspondent Name:</b>	HAMRE, SCHUMANN, MUELLER & LARSON, P.C.
<b>Address Line 1:</b>	45 SOUTH SEVENTH STREET, SUITE 2700
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402
<b>ATTORNEY DOCKET NUMBER:</b>	13496.0024USWO
<b>NAME OF SUBMITTER:</b>	RONG YANG
<b>SIGNATURE:</b>	/rongcyang/
<b>DATE SIGNED:</b>	06/25/2018

**Total Attachments: 2**

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Docket No. 13496.0024USWO

## ASSIGNMENT OF PATENT APPLICATION

WHEREAS,

1. **Guangwei XU** having an address of No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029 China
2. **Zhiheng HAN** having an address of No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029 China
3. **Wei WANG** having an address of No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029 China
4. **Congyan LU** having an address of No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029 China
5. **Lingfei WANG** having an address of No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029 China
6. **Ling LI** having an address of No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029 China
7. **Ming LIU** having an address of No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029 China

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on \_\_\_\_\_, entitled **METHOD FOR ACQUIRING CONTACT RESISTANCE OF PLANAR DEVICE**, and which has been given application serial number \_\_\_\_\_;

and

WHEREAS **INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES** (hereinafter "ASSIGNEE") a corporation organized under the laws of China and having an office and place of business at No. 3 Beitucheng West Road, Chaoyang District, Beijing, 100029, China wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEE, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all

Letters Patent for said invention to the ASSIGNEE of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Guangwei Xu  
Guangwei XU

2018.5.24  
Date

Zhiheng HAN  
Zhiheng HAN

2018.5.24  
Date

Wei WANG  
Wei WANG

2018.5.24  
Date

Congyan Lu  
Congyan LU

2018.5.24  
Date

Lingfei WANG  
Lingfei WANG

2018.5.24  
Date

Ling LI  
Ling LI

2018.5.24  
Date

Ming LIU  
Ming LIU

2018.5.24  
Date